What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	55MHz
Connectivity	EBI/EMI, I²C, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	88
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.65V ~ 1.95V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	128-LQFP
Supplier Device Package	128-LQFP (20x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at91sam7se512b-au

- **Provides Reset or Interrupt Signals to the System**
  - **Counter May Be Stopped While the Processor is in Debug State or in Idle Mode**
- **Real-time Timer (RTT)**
  - **32-bit Free-running Counter with Alarm**
  - **Runs Off the Internal RC Oscillator**
- **Three Parallel Input/Output Controllers (PIO)**
  - **Eighty-eight Programmable I/O Lines Multiplexed with up to Two Peripheral I/Os**
  - **Input Change Interrupt Capability on Each I/O Line**
  - **Individually Programmable Open-drain, Pull-up Resistor and Synchronous Output**
  - **Schmitt Trigger on All inputs**
- **Eleven Peripheral DMA Controller (PDC) Channels**
- **One USB 2.0 Full Speed (12 Mbits per second) Device Port**
  - **On-chip Transceiver, Eight Endpoints, 2688-byte Configurable Integrated FIFOs**
- **One Synchronous Serial Controller (SSC)**
  - **Independent Clock and Frame Sync Signals for Each Receiver and Transmitter**
  - **I²S Analog Interface Support, Time Division Multiplex Support**
  - **High-speed Continuous Data Stream Capabilities with 32-bit Data Transfer**
- **Two Universal Synchronous/Asynchronous Receiver Transmitters (USART)**
  - **Individual Baud Rate Generator, IrDA® Infrared Modulation/Demodulation**
  - **Support for ISO7816 T0/T1 Smart Card, Hardware Handshaking, RS485 Support**
  - **Full Modem Line Support on USART1**
- **One Master/Slave Serial Peripheral Interfaces (SPI)**
  - **8- to 16-bit Programmable Data Length, Four External Peripheral Chip Selects**
- **One Three-channel 16-bit Timer/Counter (TC)**
  - **Three External Clock Inputs, Two Multi-purpose I/O Pins per Channel**
  - **Double PWM Generation, Capture/Waveform Mode, Up/Down Capability**
- **One Four-channel 16-bit PWM Controller (PWMC)**
- **One Two-wire Interface (TWI)**
  - **Master, Multi-Master and Slave Mode Support, All Two-wire Atmel EEPROMs Supported**
  - **General Call Supported in Slave Mode**
- **One 8-channel 10-bit Analog-to-Digital Converter, Four Channels Multiplexed with Digital I/Os**
- **SAM-BA®**
  - **Default Boot program**
  - **Interface with SAM-BA Graphic User Interface**
- **IEEE® 1149.1 JTAG Boundary Scan on All Digital Pins**
- **Four High-current Drive I/O lines, Up to 16 mA Each**
- **Power Supplies**
  - **Embedded 1.8V Regulator, Drawing up to 100 mA for the Core and External Components**
  - **1.8V or 3,3V VDDIO I/O Lines Power Supply, Independent 3.3V VDDFLASH Flash Power Supply**
  - **1.8V VDDCORE Core Power Supply with Brownout Detector**
- **Fully Static Operation:**
  - **Up to 55 MHz at 1.8V and 85° C Worst Case Conditions**
  - **Up to 48 MHz at 1.65V and 85° C Worst Case Conditions**
- **Available in a 128-lead LQFP Green Package, or a 144-ball LFBGA RoHS-compliant Package**

2. Block Diagram

Figure 2-1. SAM7SE512/256/32 Block Diagram Signal Description

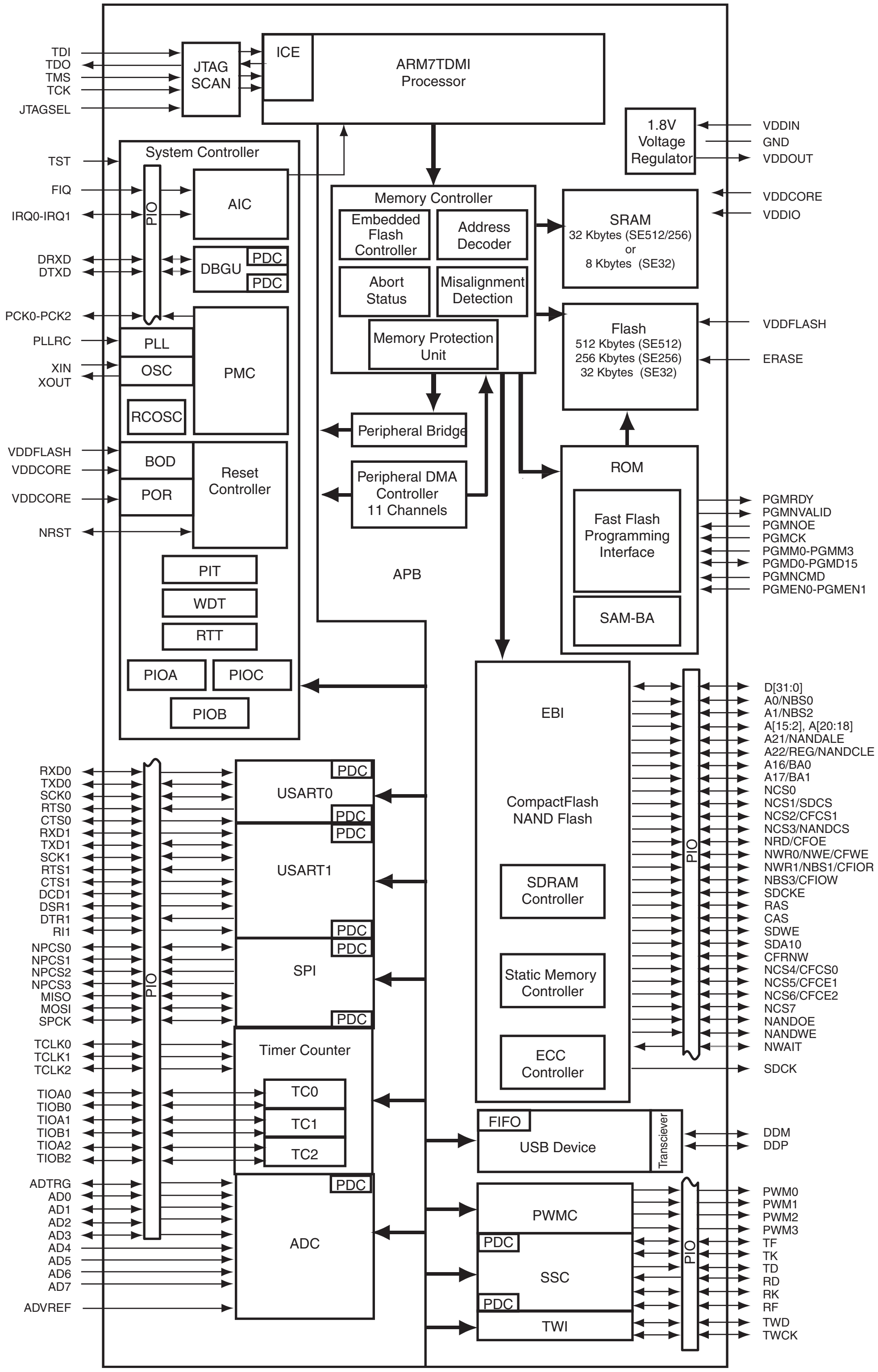


Table 3-1. Signal Description List (Continued)

Signal Name	Function	Type	Active Level	Comments
EBI for NAND Flash Support				
NANDCS	NAND Flash Chip Select Line	Output	Low	
NANDOE	NAND Flash Output Enable	Output	Low	
NANDWE	NAND Flash Write Enable	Output	Low	
NANDCLE	NAND Flash Command Line Enable	Output	Low	
NANDALE	NAND Flash Address Line Enable	Output	Low	
SDRAM Controller				
SDCK	SDRAM Clock	Output		Tied low after reset
SDCKE	SDRAM Clock Enable	Output	High	
SDCS	SDRAM Controller Chip Select Line	Output	Low	
BA[1:0]	Bank Select	Output		
SDWE	SDRAM Write Enable	Output	Low	
RAS - CAS	Row and Column Signal	Output	Low	
NBS[3:0]	Byte Mask Signals	Output	Low	
SDA10	SDRAM Address 10 Line	Output		

Note: 1. Refer to Section 6. "/O Lines Considerations" on page 15.

4. Package

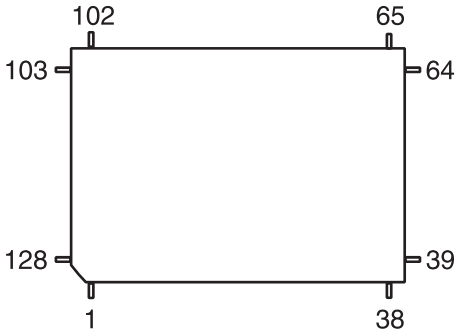
The SAM7SE512/256/32 is available in:

- 20 x 14 mm 128-lead LQFP package with a 0.5 mm lead pitch.
- 10x 10 x 1.4 mm 144-ball LFBGA package with a 0.8 mm lead pitch

4.1 128-lead LQFP Package Outline

Figure 4-1 shows the orientation of the 128-lead LQFP package and a detailed mechanical description is given in the Mechanical Characteristics section of the full datasheet.

Figure 4-1. 128-lead LQFP Package Outline (Top View)



4.2 128-lead LQFP Pinout

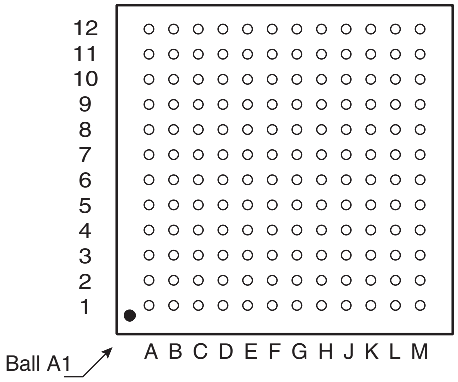
Table 4-1. Pinout in 128-lead LQFP Package

1	ADVREF	33	PB31	65	TDI	97	SDCK
2	GND	34	PB30	66	TDO	98	PC8
3	AD7	35	PB29	67	PB2	99	PC7
4	AD6	36	PB28	68	PB1	100	PC6
5	AD5	37	PB27	69	PB0	101	PC5
6	AD4	38	PB26	70	GND	102	PC4
7	VDDOUT	39	PB25	71	VDDIO	103	PC3
8	VDDIN	40	PB24	72	VDDCORE	104	PC2
9	PA20/PGMD8/AD3	41	PB23	73	NRST	105	PC1
10	PA19/PGMD7/AD2	42	PB22	74	TST	106	PC0
11	PA18/PGMD6/AD1	43	PB21	75	ERASE	107	PA31
12	PA17/PGMD5/AD0	44	PB20	76	TCK	108	PA30
13	PA16/PGMD4	45	GND	77	TMS	109	PA29
14	PA15/PGMD3	46	VDDIO	78	JTAGSEL	110	PA28
15	PA14/PGMD2	47	VDDCORE	79	PC23	111	PA27/PGMD15
16	PA13/PGMD1	48	PB19	80	PC22	112	PA26/PGMD14
17	PA12/PGMD0	49	PB18	81	PC21	113	PA25/PGMD13
18	PA11/PGMM3	50	PB17	82	PC20	114	PA24/PGMD12
19	PA10/PGMM2	51	PB16	83	PC19	115	PA23/PGMD11
20	PA9/PGMM1	52	PB15	84	PC18	116	PA22/PGMD10
21	VDDIO	53	PB14	85	PC17	117	PA21/PGMD9
22	GND	54	PB13	86	PC16	118	VDDCORE
23	VDDCORE	55	PB12	87	PC15	119	GND
24	PA8/PGMM0	56	PB11	88	PC14	120	VDDIO
25	PA7/PGMNVALID	57	PB10	89	PC13	121	DM
26	PA6/PGMNOE	58	PB9	90	PC12	122	DP
27	PA5/PGMRDY	59	PB8	91	PC11	123	VDDFLASH
28	PA4/PGMNCMD	60	PB7	92	PC10	124	GND
29	PA3	61	PB6	93	PC9	125	XIN/PGMCK
30	PA2/PGMEN2	62	PB5	94	GND	126	XOUT
31	PA1/PGMEN1	63	PB4	95	VDDIO	127	PLLRC
32	PA0/PGMEN0	64	PB3	96	VDDCORE	128	VDDPLL

4.3 144-ball LFBGA Package Outline

Figure 4-2 shows the orientation of the 144-ball LFBGA package and a detailed mechanical description is given in the Mechanical Characteristics section.

Figure 4-2. 144-ball LFBGA Package Outline (Top View)



4.4 144-ball LFBGA Pinout

Table 4-2. SAM7SE512/256/32 Pinout for 144-ball LFBGA Package

Pin	Signal Name
A1	PB7
A2	PB8
A3	PB9
A4	PB12
A5	PB13
A6	PB16
A7	PB22
A8	PB23
A9	PB25
A10	PB29
A11	PB30
A12	PB31
B1	PB6
B2	PB3
B3	PB4
B4	PB10
B5	PB14
B6	PB18
B7	PB20
B8	PB24
B9	PB28
B10	PA4/PGMNCMD
B11	PA0/PGMEN0
B12	PA1/PGMEN1
C1	PB0
C2	PB1
C3	PB5
C4	PB11
C5	PB15
C6	PB19
C7	PB21
C8	PB27
C9	PA6/PGMNOE
C10	PA5/PGMRDY
C11	PA2/PGMEN2
C12	PA3
D1	VDDCORE
D2	VDDCORE
D3	PB2
D4	TDO
D5	TDI
D6	PB17
D7	PB26
D8	PA14/PGMD2
D9	PA12/PGMD0
D10	PA11/PGMM3
D11	PA8/PGMM0
D12	PA7/PGMNVALID
E1	PC22
E2	PC23
E3	NRST
E4	TCK
E5	ERASE
E6	TEST
E7	VDDCORE
E8	VDDCORE
E9	GND
E10	PA9/PGMM1
E11	PA10/PGMM2
E12	PA13/PGMD1
F1	PC21
F2	PC20
F3	PC19
F4	JTAGSEL
F5	TMS
F6	VDDIO
F7	GND
F8	GND
F9	GND
F10	AD5
F11	PA15/PGMD3
F12	PA16/PGMD4
G1	PC18
G2	PC16
G3	PC17
G4	PC9
G5	VDDIO
G6	GND
G7	GND
G8	GND
G9	GND
G10	AD4
G11	VDDIN
G12	VDDOUT
H1	PC15
H2	PC14
H3	PC13
H4	VDDCORE
H5	VDDCORE
H6	GND
H7	GND
H8	GND
H9	GND
H10	PA19/PGMD7/AD2
H11	PA20/PGMD8/AD3
H12	VDDIO
J1	PC12
J2	PC10
J3	PA30
J4	PA28
J5	PA23/PGMD11
J6	PA22/PGMD10
J7	AD6
J8	AD7
J9	VDDCORE
J10	VDDCORE
J11	VDDCORE
J12	VDDIO
K1	PC11
K2	PC6
K3	PC2
K4	PC0
K5	PA27/PGMD15
K6	PA26/PGMD14
K7	GND
K8	VDDCORE
K9	VDDFLASH
K10	VDDIO
K11	VDDIO
K12	PA18/PGMD6/AD1
L1	SDCK
L2	PC7
L3	PC4
L4	PC1
L5	PA29
L6	PA24/PGMD12
L7	PA21/PGMD9
L8	ADVREF
L9	VDDFLASH
L10	VDDFLASH
L11	PA17/PGMD5/AD0
L12	GND
M1	PC8
M2	PC5
M3	PC3
M4	PA31
M5	PA25/PGMD13
M6	DM
M7	DP
M8	GND
M9	XIN/PGMCK
M10	XOUT
M11	PLLRC
M12	VDDPLL

5. Power Considerations

5.1 Power Supplies

The SAM7SE512/256/32 has six types of power supply pins and integrates a voltage regulator, allowing the device to be supplied with only one voltage. The six power supply pin types are:

- VDDIN pin. It powers the voltage regulator and the ADC; voltage ranges from 3.0V to 3.6V, 3.3V nominal.
- VDDOUT pin. It is the output of the 1.8V voltage regulator.
- VDDIO pin. It powers the I/O lines; two voltage ranges are supported:
  - from 3.0V to 3.6V, 3.3V nominal
  - or from 1.65V to 1.95V, 1.8V nominal.
- VDDFLASH pin. It powers the USB transceivers and a part of the Flash. It is required for the Flash to operate correctly; voltage ranges from 3.0V to 3.6V, 3.3V nominal.
- VDDCORE pins. They power the logic of the device; voltage ranges from 1.65V to 1.95V, 1.8V typical. It can be connected to the VDDOUT pin with decoupling capacitor. VDDCORE is required for the device, including its embedded Flash, to operate correctly.
- VDDPLL pin. It powers the oscillator and the PLL. It can be connected directly to the VDDOUT pin.

In order to decrease current consumption, if the voltage regulator and the ADC are not used, VDDIN, ADVREF, AD4, AD5, AD6 and AD7 should be connected to GND. In this case VDDOUT should be left unconnected.

No separate ground pins are provided for the different power supplies. Only GND pins are provided and should be connected as shortly as possible to the system ground plane.

5.2 Power Consumption

The SAM7SE512/256/32 has a static current of less than 60 µA on VDDCORE at 25°C, including the RC oscillator, the voltage regulator and the power-on reset when the brownout detector is deactivated. Activating the brownout detector adds 20 µA static current.

The dynamic power consumption on VDDCORE is less than 80 mA at full speed when running out of the Flash. Under the same conditions, the power consumption on VDDFLASH does not exceed 10 mA.

5.3 Voltage Regulator

The SAM7SE512/256/32 embeds a voltage regulator that is managed by the System Controller.

In Normal Mode, the voltage regulator consumes less than 100 µA static current and draws 100 mA of output current.

The voltage regulator also has a Low-power Mode. In this mode, it consumes less than 20 µA static current and draws 1 mA of output current.

Adequate output supply decoupling is mandatory for VDDOUT to reduce ripple and avoid oscillations. The best way to achieve this is to use two capacitors in parallel:

- One external 470 pF (or 1 nF) NPO capacitor should be connected between VDDOUT and GND as close to the chip as possible.

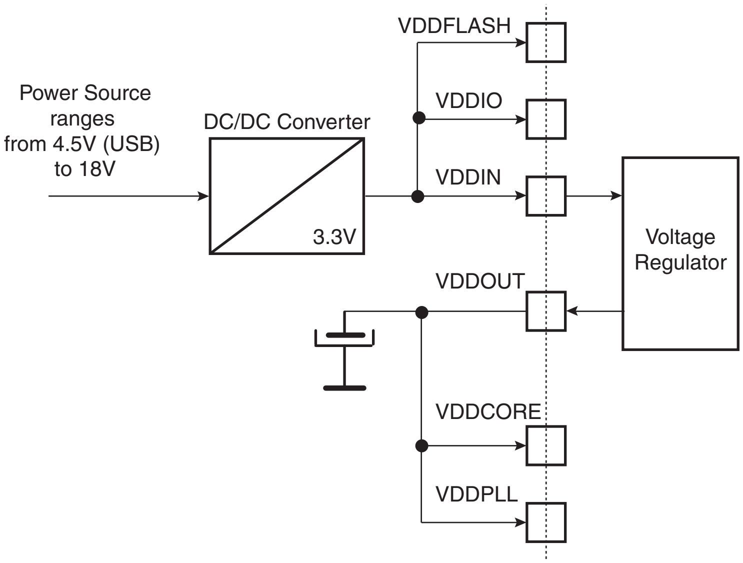
- One external 2.2 µF (or 3.3 µF) X7R capacitor should be connected between VDDOUT and GND.

Adequate input supply decoupling is mandatory for VDDIN in order to improve startup stability and reduce source voltage drop. The input decoupling capacitor should be placed close to the chip. For example, two capacitors can be used in parallel: 100 nF NPO and 4.7 µF X7R.

5.4 Typical Powering Schematics

The SAM7SE512/256/32 supports a 3.3V single supply mode. The internal regulator input connected to the 3.3V source and its output feeds VDDCORE and the VDDPLL. Figure 5-1 shows the power schematics to be used for USB bus-powered systems.

Figure 5-1. 3.3V System Single Power Supply Schematic



7.8 Peripheral DMA Controller

- Handles data transfer between peripherals and memories
- Eleven channels
  - Two for each USART
  - Two for the Debug Unit
  - Two for the Serial Synchronous Controller
  - Two for the Serial Peripheral Interface
  - One for the Analog-to-digital Converter
- Low bus arbitration overhead
  - One Master Clock cycle needed for a transfer from memory to peripheral
  - Two Master Clock cycles needed for a transfer from peripheral to memory
- Next Pointer management for reducing interrupt latency requirements
- Peripheral DMA Controller (PDC) priority is as follows (from the highest priority to the lowest):

Receive	DBGU
Receive	USART0
Receive	USART1
Receive	SSC
Receive	ADC
Receive	SPI
Transmit	DBGU
Transmit	USART0
Transmit	USART1
Transmit	SSC
Transmit	SPI

8. Memories

- 512 Kbytes of Flash Memory (SAM7SE512)
  - dual plane
  - two contiguous banks of 1024 pages of 256 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 32 lock bits, each protecting 32 lock regions of 64 pages
  - Protection Mode to secure contents of the Flash
- 256 Kbytes of Flash Memory (SAM7SE256)
  - single plane
  - one bank of 1024 pages of 256 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 cycles, 10-year data retention capability
  - 16 lock bits, each protecting 16 lock regions of 64 pages
  - Protection Mode to secure contents of the Flash
- 32 Kbytes of Flash Memory (SAM7SE32)
  - single plane
  - one bank of 256 pages of 128 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 cycles, 10-year data retention capability
  - 8 lock bits, each protecting 8 lock regions of 32 pages
  - Protection Mode to secure contents of the Flash
- 32 Kbytes of Fast SRAM (SAM7SE512/256)
  - Single-cycle access at full speed
- 8 Kbytes of Fast SRAM (SAM7SE32)
  - Single-cycle access at full speed

Figure 8-2. Internal Memory Mapping with GPNVM Bit 2 = 0 (default)

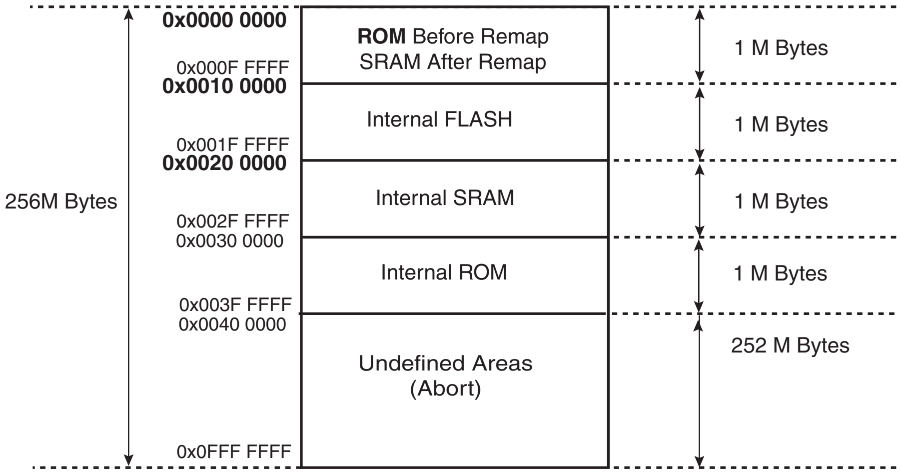
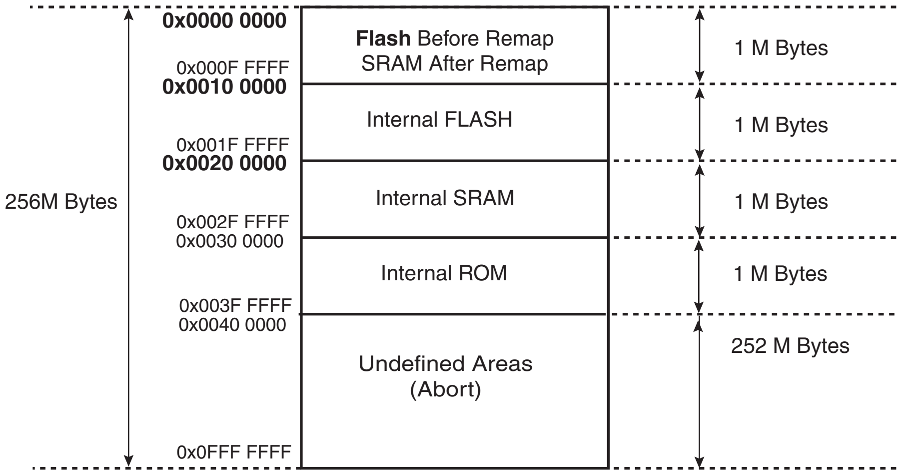


Figure 8-3. Internal Memory Mapping with GPNVM Bit 2 = 1



8.1.2 Embedded Flash

8.1.2.1 Flash Overview

The Flash of the SAM7SE512 is organized in two banks (dual plane) of 1024 pages of 256 bytes. It reads as 131,072 32-bit words.

The Flash of the SAM7SE256 is organized in 1024 pages (single plane) of 256 bytes. It reads as 65,536 32-bit words.

The Flash of the SAM7SE32 is organized in 256 pages (single plane) of 128 bytes. It reads as 8192 32-bit words.

The Flash of the SAM7SE32 contains a 128-byte write buffer, accessible through a 32-bit interface.

The Flash of the SAM7SE512/256 contains a 256-byte write buffer, accessible through a 32-bit interface.

The security bit can only be enabled through the Command “Set Security Bit” of the EFC User Interface. Disabling the security bit can only be achieved by asserting the ERASE pin at 1 and after a full flash erase is performed. When the security bit is deactivated, all accesses to the flash are permitted.

It is important to note that the assertion of the ERASE pin should always be longer than 200 ms.

As the ERASE pin integrates a permanent pull-down, it can be left unconnected during normal operation. However, it is safer to connect it directly to GND for the final application.

8.1.2.5 Non-volatile Brownout Detector Control

Two general purpose NVM (GPNVM) bits are used for controlling the brownout detector (BOD), so that even after a power loss, the brownout detector operations remain in their state.

These two GPNVM bits can be cleared or set respectively through the commands “Clear General-purpose NVM Bit” and “Set General-purpose NVM Bit” of the EFC User Interface.

- GPNVM bit 0 is used as a brownout detector enable bit. Setting the GPNVM bit 0 enables the BOD, clearing it disables the BOD. Asserting ERASE clears the GPNVM bit 0 and thus disables the brownout detector by default.
- GPNVM bit 1 is used as a brownout reset enable signal for the reset controller. Setting the GPNVM bit 1 enables the brownout reset when a brownout is detected, Clearing the GPNVM bit 1 disables the brownout reset. Asserting ERASE disables the brownout reset by default.

8.1.2.6 Calibration Bits

Sixteen NVM bits are used to calibrate the brownout detector and the voltage regulator. These bits are factory configured and cannot be changed by the user. The ERASE pin has no effect on the calibration bits.

8.1.3 Fast Flash Programming Interface

The Fast Flash Programming Interface allows programming the device through either a serial JTAG interface or through a multiplexed fully-handshaked parallel port. It allows gang-programming with market-standard industrial programmers.

The FFPI supports read, page program, page erase, full erase, lock, unlock and protect commands.

The Fast Flash Programming Interface is enabled and the Fast Programming Mode is entered when the TST pin and the PA0 and PA1 pins are all tied high and PA2 tied to low.

- The Flash of the SAM7SE512 is organized in 2048 pages of 256 bytes (dual plane). It reads as 131,072 32-bit words.
- The Flash of the SAM7SE256 is organized in 1024 pages of 256 bytes (single plane). It reads as 65,536 32-bit words.
- The Flash of the SAM7SE32 is organized in 256 pages of 128 bytes (single plane). It reads as 32,768 32-bit words.
- The Flash of the SAM7SE512/256 contains a 256-byte write buffer, accessible through a 32-bit interface.
- The Flash of the SAM7SE32 contains a 128-byte write buffer, accessible through a 32-bit interface.

8.1.4 SAM-BA® Boot

The SAM-BA Boot is a default Boot Program which provides an easy way to program in-situ the on-chip Flash memory.

The SAM-BA Boot Assistant supports serial communication via the DBGU or the USB Device Port.

- Communication via the DBGU supports a wide range of crystals from 3 to 20 MHz via software auto-detection.
- Communication via the USB Device Port is limited to an 18.432 MHz crystal.

The SAM-BA Boot provides an interface with SAM-BA Graphic User Interface (GUI).

The SAM-BA Boot is in ROM and is mapped in Flash at address 0x0 when GPNVM bit 2 is set to 0.

8.2 External Memories

The external memories are accessed through the External Bus Interface.

Refer to the memory map in Figure 8-1 on page 22.

9. System Controller

The System Controller manages all vital blocks of the microcontroller: interrupts, clocks, power, time, debug and reset.

The System Controller peripherals are all mapped to the highest 4 Kbytes of address space, between addresses 0xFFFF F000 and 0xFFFF FFFF.

Figure 9-1 on page 29 shows the System Controller Block Diagram.

Figure 8-1 on page 22 shows the mapping of the User Interface of the System Controller peripherals. Note that the Memory Controller configuration user interface is also mapped within this address space.

- Synchronous output, provides Set and Clear of several I/O lines in a single write

9.10 Voltage Regulator Controller

The purpose of this controller is to select the Power Mode of the Voltage Regulator between Normal Mode (bit 0 is cleared) or Standby Mode (bit 0 is set).

10.4 PIO Controller A Multiplexing

Table 10-2. Multiplexing on PIO Controller A

PIO Controller A				Application Usage	
I/O Line	**Peripheral A**	**Peripheral B**	**Comments**	**Function**	**Comments**
PA0	PWM0	A0/NBS0	High-Drive		
PA1	PWM1	A1/NBS2	High-Drive		
PA2	PWM2	A2	High-Drive		
PA3	TWD	A3	High-Drive		
PA4	TWCK	A4			
PA5	RXD0	A5			
PA6	TXD0	A6			
PA7	RTS0	A7			
PA8	CTS0	A8			
PA9	DRXD	A9			
PA10	DTXD	A10			
PA11	NPCS0	A11			
PA12	MISO	A12			
PA13	MOSI	A13			
PA14	SPCK	A14			
PA15	TF	A15			
PA16	TK	A16/BA0			
PA17	TD	A17/BA1	AD0		
PA18	RD	NBS3/CFIOW	AD1		
PA19	RK	NCS4/CFCS0	AD2		
PA20	RF	NCS2/CFCS1	AD3		
PA21	RXD1	NCS6/CFCE2			
PA22	TXD1	NCS5/CFCE1			
PA23	SCK1	NWR1/NBS1/CFIOR			
PA24	RTS1	SDA10			
PA25	CTS1	SDCKE			
PA26	DCD1	NCS1/SDCS			
PA27	DTR1	SDWE			
PA28	DSR1	CAS			
PA29	RI1	RAS			
PA30	IRQ1	D30			
PA31	NPCS1	D31			

10.5 PIO Controller B Multiplexing

Table 10-3. Multiplexing on PIO Controller B

PIO Controller B				Application Usage	
I/O Line	**Peripheral A**	**Peripheral B**	**Comments**	**Function**	**Comments**
PB0	TIOA0	A0/NBS0			
PB1	TIOB0	A1/NBS2			
PB2	SCK0	A2			
PB3	NPCS3	A3			
PB4	TCLK0	A4			
PB5	NPCS3	A5			
PB6	PCK0	A6			
PB7	PWM3	A7			
PB8	ADTRG	A8			
PB9	NPCS1	A9			
PB10	NPCS2	A10			
PB11	PWM0	A11			
PB12	PWM1	A12			
PB13	PWM2	A13			
PB14	PWM3	A14			
PB15	TIOA1	A15			
PB16	TIOB1	A16/BA0			
PB17	PCK1	A17/BA1			
PB18	PCK2	D16			
PB19	FIQ	D17			
PB20	IRQ0	D18			
PB21	PCK1	D19			
PB22	NPCS3	D20			
PB23	PWM0	D21			
PB24	PWM1	D22			
PB25	PWM2	D23			
PB26	TIOA2	D24			
PB27	TIOB2	D25			
PB28	TCLK1	D26			
PB29	TCLK2	D27			
PB30	NPCS2	D28			
PB31	PCK2	D29			

  - 8- to 16-bit programmable data length per chip select
  - Programmable phase and polarity per chip select
  - Programmable transfer delays per chip select, between consecutive transfers and between clock and data
  - Programmable delay between consecutive transfers
  - Selectable mode fault detection
  - Maximum frequency at up to Master Clock

10.8 Two Wire Interface

- Master, Multi-Master and Slave Mode Operation
- Compatibility with standard two-wire serial memories
- One, two or three bytes for slave address
- Sequential read/write operations
- Bit Rate: Up to 400 Kbit/s
- General Call Supported in Slave Mode

10.9 USART

- Programmable Baud Rate Generator
- 5- to 9-bit full-duplex synchronous or asynchronous serial communications
  - 1, 1.5 or 2 stop bits in Asynchronous Mode
  - 1 or 2 stop bits in Synchronous Mode
  - Parity generation and error detection
  - Framing error detection, overrun error detection
  - MSB or LSB first
  - Optional break generation and detection
  - By 8 or by 16 over-sampling receiver frequency
  - Hardware handshaking RTS - CTS
  - Modem Signals Management DTR-DSR-DCD-RI on USART1
  - Receiver time-out and transmitter timeguard
  - Multi-drop Mode with address generation and detection
- RS485 with driver control signal
- ISO7816, T = 0 or T = 1 Protocols for interfacing with smart cards
  - NACK handling, error counter with repetition and iteration limit
- IrDA® modulation and demodulation
  - Communication at up to 115.2 Kbps
- Test Modes
  - Remote Loopback, Local Loopback, Automatic Echo

10.10 Serial Synchronous Controller

- Provides serial synchronous communication links used in audio and telecom applications
- Contains an independent receiver and transmitter and a common clock divider

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